



## Material Interconnections and Microstructure Control-Related

Guest Editor:

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### Message from the Guest Editor

Dear Colleagues,

The advancement of electronic devices requires new interconnection materials, which should possess excellent electric/thermal conductivity as well as high robustness. New interconnection materials/technologies and their control methods must be established based on scientific understanding of hetero-interface phenomena.

This Special Issue will focus on the current researches in interconnections and their microstructural control for advancing electronic devices, including soldering, sinter joining, conductive adhesive, alternative interconnects, metallization, substrates, 3D packaging, quality, reliability, and failure analysis.

We will assess how certain interconnect features (device metallization, interconnects, substrates, design, etc.) can influence the performance and reliability of devices. Your contributions will provide considerable impact on new electronic/optical devices.

Prof. Katsuaki Suganuma  
*Guest Editor*





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## Message from the Editor-in-Chief

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